



Click [here](#) for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 2220 |
| L | 5.9mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| T | 2.5mm +/-0.20mm |
| B | 0.6mm +/-0.35mm |

| Packaging Specifications | |
|--------------------------|--------------------------|
| Packaging | T&R, 330mm, Plastic Tape |
| Packaging Quantity | 2000 |

| General Information | |
|---------------------|--|
| Series | KC-LINK Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 320 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 6200 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 2% |
| Voltage DC | 1700 VDC |
| Dielectric Withstanding Voltage | 2040 VDC |
| Temperature Range | -55/+150°C |
| Temperature Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 100 GOhms |

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